Mihai Telescu

List of Publications by Year in descending order

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2258059 2272923 21 5 3 4 citations h-index g-index papers 5 5 5 19 citing authors docs citations times ranked all docs

#	Article	IF	CITATIONS
1	Foreword: Special Section on Packaging and Interconnects: Cutting-Edge Solutions in Modeling, Design, and Characterization—Part I. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 1667-1668.	2.5	O
2	Foreword: Special Section on Packaging and Interconnects: Cutting-Edge Solutions in Modeling, Design, and Characterization—Part II. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 1929-1930.	2. 5	1
3	Constructive Signal Approximations for Fast Transient Simulation of Coupled Channels. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 2087-2096.	2.5	4
4	Simplified topology for integrated circuit buffer behavioural models. IET Circuits, Devices and Systems, 2017, 11, 183-187.	1.4	6
5	Present and future of I/O-buffer behavioral macromodels. IEEE Electromagnetic Compatibility Magazine, 2016, 5, 79-85.	0.1	10